

WCN2-0040R6-C11-M

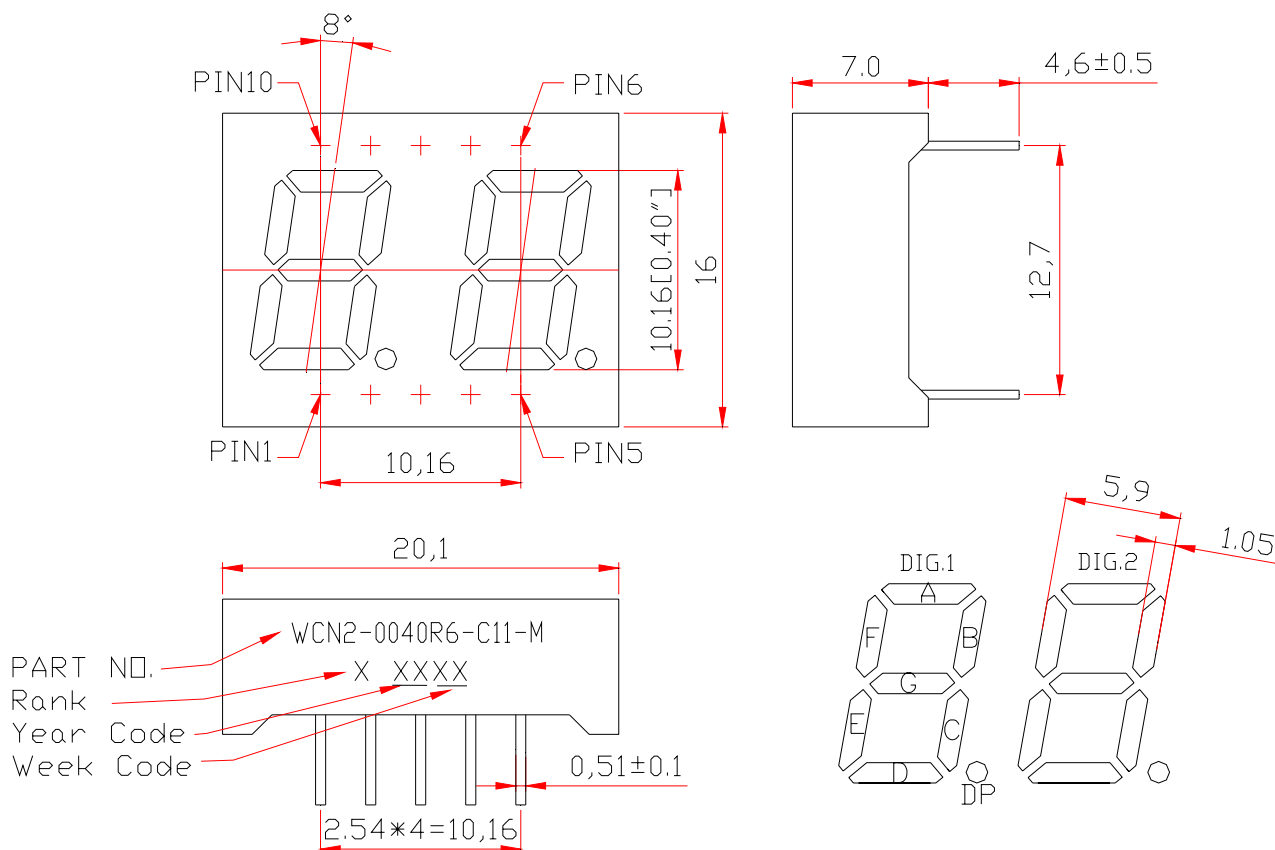
SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Zhang 2018-10-30	Athena	William	
REVISION RECORD			

**REVISION: A0**

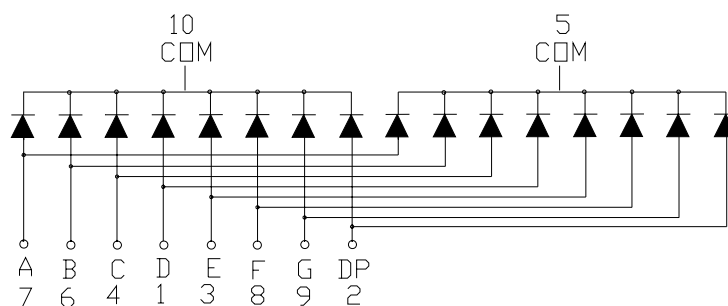
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■ **Outer Dimension:**



Notes: Unless otherwise stated, The tolerance is $\pm 0.25\text{mm}$.

■ **Circuit Diagram:**



■ Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Anode D	6	Anode B
2	Anode DP	7	Anode A
3	Anode E	8	Anode F
4	Anode C	9	Anode G
5	CommonCathodeDig.2	10	Common Cathode Dig.1

■ Features:

- High Reliability
- Color: Super Bright Red
- Low Power Requirement
- Easy Assembly

■ Description:

- Dual Digit Display
- Digit Height: 10.16mm(0.40")
- Black Face and Milky Segment

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment	P _d	—	Red	52	mW
Forward Current Per Segment	I _F	—	Red	20	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	Red	100	mA
Reverse Voltage Per Segment	V _R	—	Red	5	V
Operating Temperature Range	T _{opr}	—	—	-40~+105	°C
Storage Temperature Range	T _{stg}	—	—	-40~+105	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Segment	—	2.00	2.60	V
Reverse Current	I _R	V _R =5V	Per Segment	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Segment	6101	9500	15250	μcd
Peak Emission Wave Length	λ _P	I _F =20mA	Per Segment	—	635	—	nm
	λ _D				630		
Spectral Line Half Width	△λ	I _F =20mA	Per Segment	—	20	—	nm

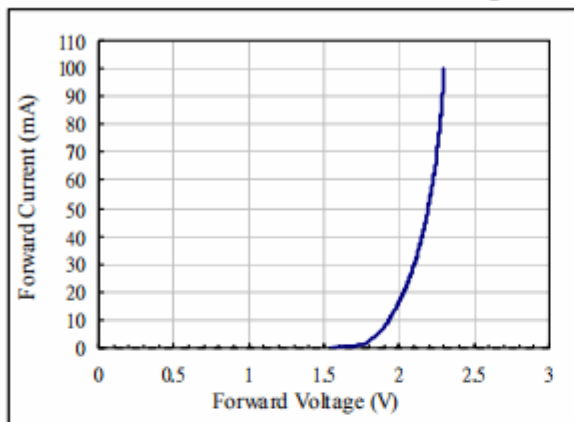
■ Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)

Rank	Symbol	Condition	Min	Max	Unit
N	N	I _F =10mA	6101	7200	μcd
O	O	I _F =10mA	7201	8500	μcd
P	P	I _F =10mA	8501	10500	μcd
Q	Q	I _F =10mA	10501	12800	μcd
R	R	I _F =10mA	12801	15250	μcd

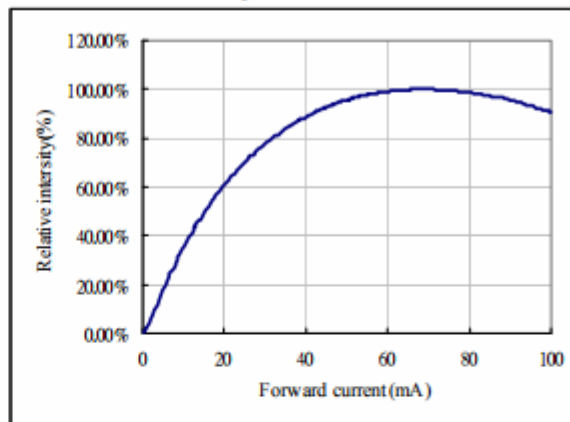
■ Soldering Conditions: Soldering Temp. ≤+260°C, Soldering Time. ≤3sec.
(at 2mm Distance from The Case of Reflector Edge)

■ Typical Elector-Optical Characteristics Curve:

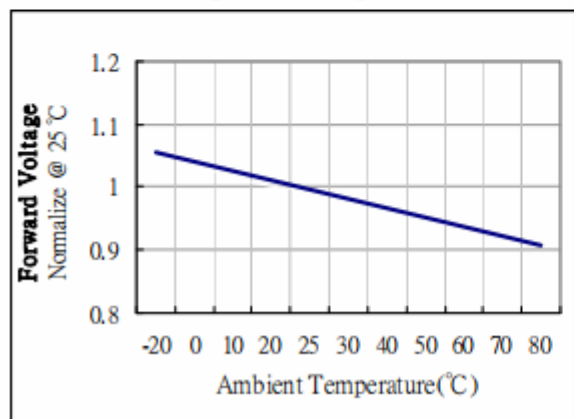
Forward current vs. Forward voltage



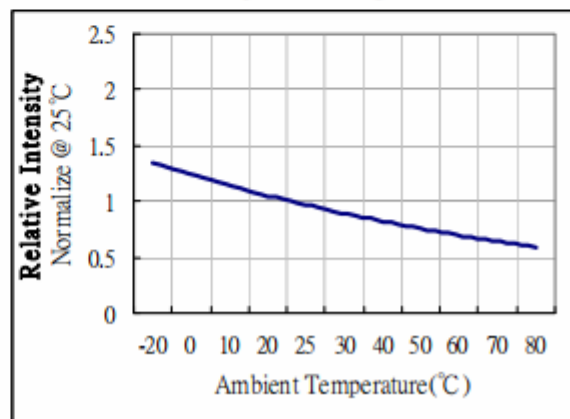
Relative intensity vs. Forward current



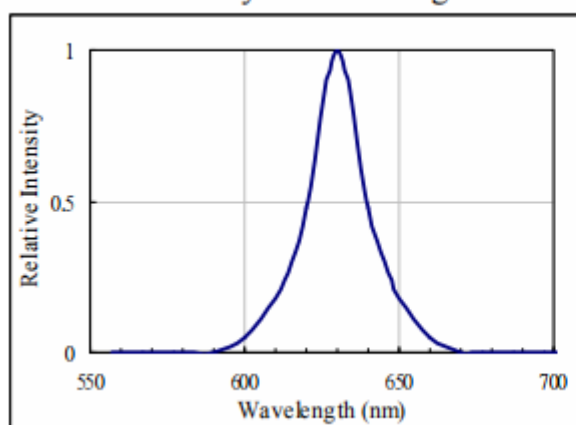
Forward voltage vs. Temperature



Relative intensity vs. Temperature



Relative intensity vs. Wavelength



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LED Displays Reliability Test:

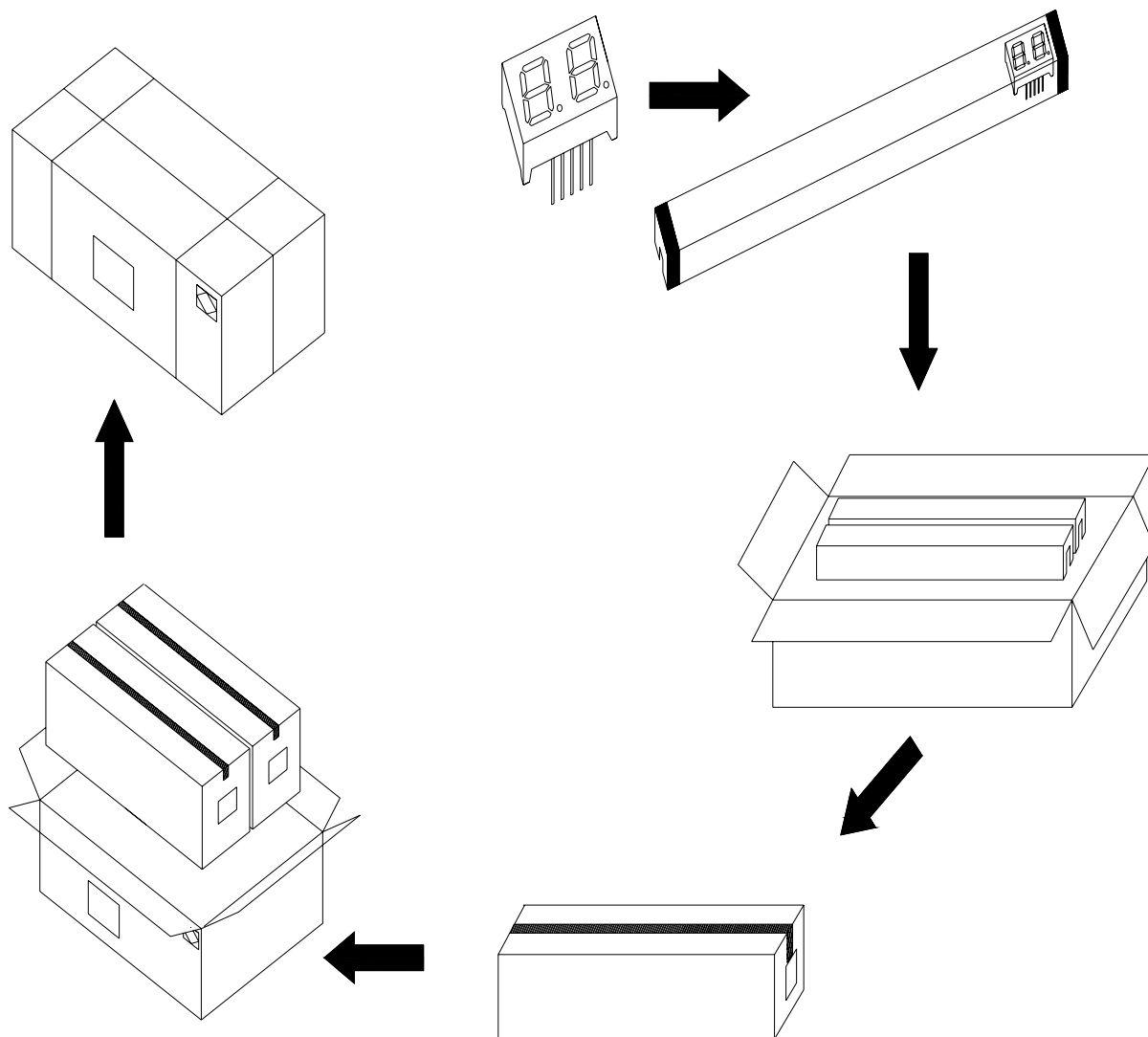
CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T_a = UNDER ROOM TEMPERATURE $I_F = I_F \text{ max}$
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY $T_a = 65 \pm 5^\circ\text{C}$ RH=90~95%RH TEST TIME=240 $\pm$ 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE $T_a = 85 \pm 5^\circ\text{C}$ (COB: $T_a = 65 \pm 5^\circ\text{C}$) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE $T_a = -35 \pm 5^\circ\text{C}$ TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION $85^\circ\text{C} \sim 25^\circ\text{C} \sim -35^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES $85 \pm 5^\circ\text{C} \sim -35 \pm 5^\circ\text{C}$ 10min 10min 10 CYCLES(COB: $T_{\text{hot}}=65^\circ\text{C}$, $T_{\text{cold}}=-25^\circ\text{C}$)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE $T_{\text{SOL}}=230 \pm 5^\circ\text{C}$ DWELL TIME=5 $\pm$ 1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING $T_{\text{SOL}}=260 \pm 5^\circ\text{C}$ DWELL TIME=10 $\pm$ 1sec.

■ Package Pattern :

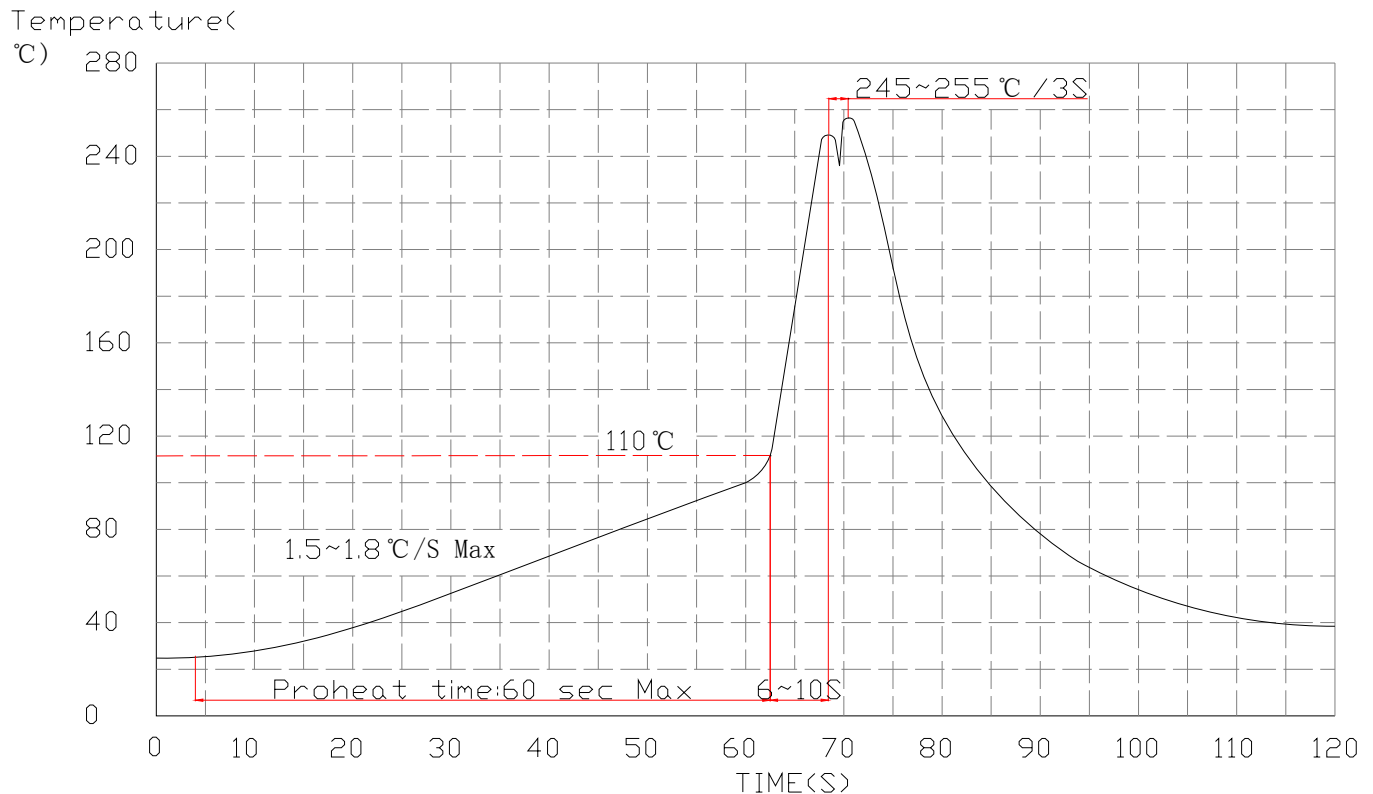
25 pcs / IC Tube.

1575 pcs / Box (537*175*125mm).

6300 pcs / Carton (550*380*280mm).



Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre-heat temperature of 110°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C.
- 2.Peak wave soldering temperature between 245°C~255°C for 3 sec .
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4.Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

Recommended Soldering Pad :

